



| ENVIRONMENTAL AND PACKAGE TESTING DATA FOR POWERPAK® MLP4535 | | | | | |
|---|--------------------|------------------------|-------------------|--------------------|------------------------|
| STRESS | SAMPLE SIZE | DEVICE HRS./CYC | CONDITION | TOTAL FAILS | FAIL PERCENTAGE |
| Bond Integrity | 80 | 40 000 | 200 °C + N2 | 0 | 0.00 |
| HAST | 328 | 32 800 | 130 °C, 85 % RH | 0 | 0.00 |
| Pressure Pot | 328 | 31 488 | 121 °C, 15 PSIG | 0 | 0.00 |
| Solder Dunk | 164 | 492 | 260 °C, 10 s | 0 | 0.00 |
| Temp. Cycle | 328 | 328 000 | -65 °C to +150 °C | 0 | 0.00 |